

Features

- Planar Die Construction
- 500mW Power Dissipation
- General Purpose, Medium Current
- Ideally Suited for Automated Assembly Processes
- Lead, Halogen and Antimony Free, RoHS Compliant**
- "Green" Device (Note 4)**
- Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOD-123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.01 grams (approximate)



Top View

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward Voltage (Note 3) @ I _F = 10mA	V _F	0.9	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1) @T _L = 75°C	P _D	500	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	R _{θJA}	350	°C/W
Thermal Resistance, Junction to Lead (Note 2)	R _{θJL}	150	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Type Number	Type Code	Zener Voltage Range (Note 3)			Test Current	Maximum Zener Impedance (Note 5)		Maximum Reverse Leakage Current (Note 3)	
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK} = 0.25mA	I _R	@ V _R
		Nom (V)	Min (V)	Max (V)	mA	Ω		μA	V
MMSZ5263B	M8	56	53.20	58.80	2.2	150	1300	0.1	43

- Notes:
- Device mounted on FR-4 substrate, single-sided, PC boards, with minimum recommended pad layout.
 - Thermal Resistance measurement obtained via infrared scan method.
 - Short duration pulse test used to minimize self-heating effect.
 - No purposefully added lead. Halogen and Antimony Free.
 - f = 1KHz.

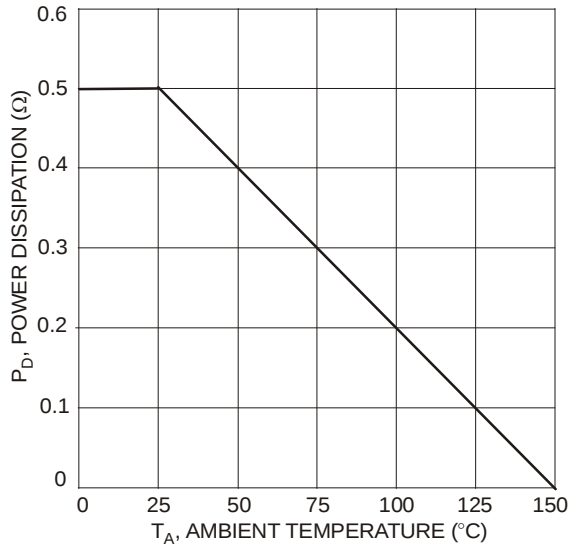


Fig. 1 Power Derating Curve

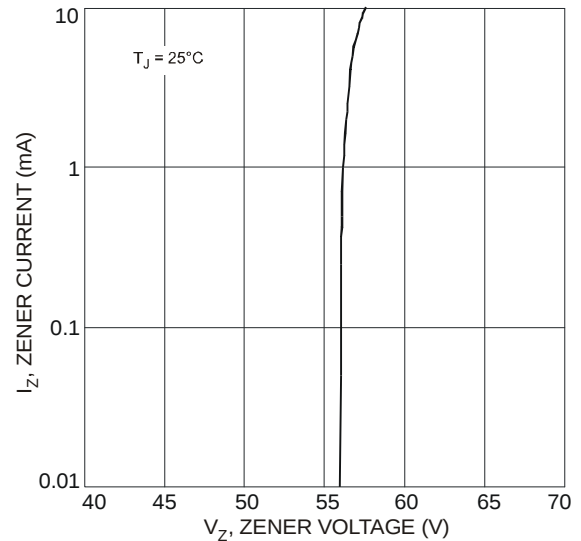


Fig. 2 Typical Zener Breakdown Characteristics

Ordering Information (Note 5)

Part Number	Packaging	Shipping
MMSZ5263B-7-F	SOD-123	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



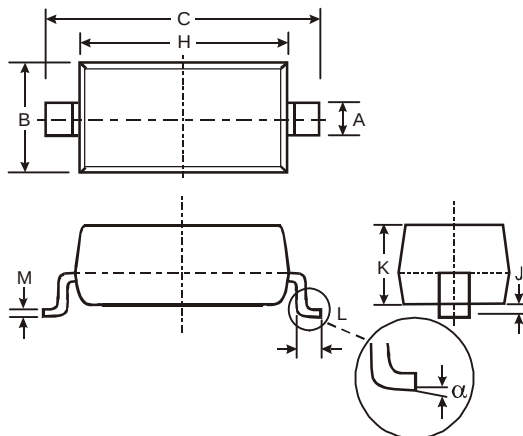
M8 = Product Type Marking Code
 (See Electrical Characteristics Table)
 YM = Date Code Marking
 Y = Year (ex: W = 2009)
 M = Month (ex: 9 = September)

Date Code Key

Year	2009	2010	2011	2012	2013	2014	2015
Code	W	X	Y	Z	A	B	C

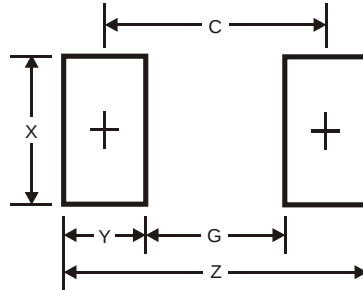
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOD-123		
Dim	Min	Max
A	0.55 Typ	
B	1.40	1.70
C	3.55	3.85
H	2.55	2.85
J	0.00	0.10
K	1.00	1.35
L	0.25	0.40
M	0.10	0.15
α	0	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	4.9
G	2.5
X	0.7
Y	1.2
C	3.7

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